

**AMENDMENTS TO THE CLAIMS**

Please replace the claims, including all prior versions, with the listing of claims found below.

**Listing of Claims:**

1-71. (Canceled)

72-79. (Withdrawn)

80. (Newly added) A semiconductor light-emitting device, comprising:  
a base substance;  
a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes; and  
a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits red light having an emission wavelength with its main emission peak in a wavelength range of 600 to 670 nm.

81. (Newly added) The semiconductor light-emitting device according to claim 80, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$M_2 O_2 S : Eu$  (M is any one or more elements selected from La, Gd and Y);

$0.5 MgF_2 \cdot 3.5 MgO \cdot GeO_2 : Mn$ ;

$Y_2 O_3 : Eu$ ;

$Y(P, V) O_4 : Eu$ ; and

$YVO_4 : Eu$ .

82. (Newly added) A semiconductor light-emitting device, comprising:  
a base substance;  
a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength in a range

of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes;  
and

a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits green light having an emission wavelength with its main emission peak in a wavelength range of 500 to 540 nm.

83. The semiconductor light-emitting device according to claim 82, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{RMg}_2\text{Al}_{16}\text{O}_{27} : \text{Eu, Mn}$  (R is any one or both elements selected from Sr and Ba);

$\text{RMgAl}_{10}\text{O}_{17} : \text{Eu, Mn}$  (R is any one or both elements selected from Sr and Ba);

$\text{ZnS} : \text{Cu}$ ;

$\text{SrAl}_2\text{O}_4 : \text{Eu}$ ;

$\text{SrAl}_2\text{O}_4 : \text{Eu, Dy}$ ;

$\text{ZnO} : \text{Zn}$ ;

$\text{Zn}_2\text{Ge}_2\text{O}_4 : \text{Mn}$ ;

$\text{Zn}_2\text{SiO}_4 : \text{Mn}$ ; and

$\text{Q}_3\text{MgSi}_2\text{O}_8 : \text{Eu, Mn}$  (Q is any one or more elements selected from Sr, Ba and Ca).

84. (Newly added) A semiconductor light-emitting device, comprising:

a base substance;

a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes;  
and

a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits blue light having an emission wavelength with its main emission peak in a wavelength range of 410 to 480 nm.

85. The semiconductor light-emitting device according to claim 84, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$A_{10}(PO_4)_6Cl_2 : Eu$  (A is any one or more elements selected from Sr, Ca, Ba, Mg and Ce);

$XMg_2Al_6O_{27} : Eu$  (X is any one or both elements selected from Sr and Ba);

$XMgAl_6O_{17} : Eu$  (X is any one or both elements selected from Sr and Ba);

$ZnS : Ag$ ;

$Sr_{10}(PO_4)_6Cl_2 : Eu$ ;

$Ca_{10}(PO_4)_6F_2 : Sb$ ;

$Z_3MgSi_2O_8 : Eu$  (Z is any one or more elements selected from Sr, Ca and Ba);

$SrMgSi_2O_8 : Eu$ ;

$Sr_2P_2O_7 : Eu$ ; and

$CaAl_2O_4 : Eu, Nd$ .

86. (Newly added) A semiconductor light-emitting device, comprising:

a base substance;

a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes; and

a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits blue green light having an emission wavelength with its main emission peak in a wavelength range of 480 to 500 nm.

87. (Newly added) The semiconductor light-emitting device according to claim 86, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$Sr_4Al_4O_{25} : Eu$ ;

$\text{Sr}_4 \text{Al}_{14} \text{O}_{25} : \text{Eu, Dy};$

$\text{L}_{10} (\text{PO}_4)_6 \text{Cl}_2 : \text{Eu}$  (L is any one or more elements selected from Ba, Ca and Mg);

and

$\text{Sr}_2 \text{Si}_3 \text{O}_8 \cdot 2\text{SrCl}_2 : \text{Eu}.$

88. (Newly added) A semiconductor light-emitting device, comprising:

a base substance;

a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having an emission wavelength in a range of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes; and

a fluorescent substance that is excited by the outgoing light from the semiconductor light-emitting element and emits orange light having an emission wavelength with its main emission peak in a wavelength range of 570 to 600 nm.

89. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein the fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{ZnS: Mn};$  and

$\text{ZnS: Cu, Mn, Co}.$

90. (Newly added) The semiconductor light-emitting device according to Claim 89, wherein a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and the sealing resin includes the fluorescent substance.

91. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein a sealing resin for sealing at least a part of the base substance and the semiconductor light-emitting element is included; and

the sealing resin includes the fluorescent substance.

92. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein  
a sealing resin for sealing at least a part of the base substance and the semiconductor  
light-emitting element is included; and  
the sealing resin includes the fluorescent substance.

93. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein  
a sealing resin for sealing at least a part of the base substance and the semiconductor  
light-emitting element is included; and  
the sealing resin includes the fluorescent substance.

94. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein  
a sealing resin for sealing at least a part of the base substance and the semiconductor  
light-emitting element is included; and  
the sealing resin includes the fluorescent substance.

95. (Newly added) The semiconductor light-emitting device according to Claim 90, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped  
mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
and  
at least a part of the two lead frames and the semiconductor light-emitting element  
are sealed with the sealing resin.

96. (Newly added) The semiconductor light-emitting device according to Claim 90, wherein  
the base substance is an insulator connected to ends of a pair of lead frames;  
the semiconductor light-emitting element is connected to metallic wiring formed on  
the insulator; and

at least a part of the pair of lead frames, the insulator and the semiconductor light-emitting element are sealed with the sealing resin.

97. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
the fluorescent substance is filled in the cup-shaped mount section; and  
at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

98. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
the fluorescent substance is filled in the cup-shaped mount section; and  
at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

99. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
the fluorescent substance is filled in the cup-shaped mount section; and  
at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

100. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein  
the base substance is a lead frame having a cup-shaped mount section;

the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
the fluorescent substance is filled in the cup-shaped mount section; and  
at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

101. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
the fluorescent substance is filled in the cup-shaped mount section; and  
at least a part of the two lead frames, the semiconductor light-emitting element and the fluorescent substance are sealed with a sealing resin.

102. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and  
at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

103. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and

at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

104. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and  
at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

105. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and  
at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.

106. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein  
the base substance is a lead frame having a cup-shaped mount section;  
the semiconductor light-emitting element is disposed at the bottom of the cup-shaped mount section of the lead frame and electrically connected to another lead frame by wire bonding;  
a coating member is filled in the cup-shaped mount section and the fluorescent substance is disposed on the coating member; and  
at least a part of the two lead frames, the semiconductor light-emitting element, the coating member and the fluorescent substance are sealed with a sealing resin.



107. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected the metallic wiring  
on the substrate;  
a sealing resin for sealing the semiconductor light-emitting element is included; and  
the sealing resin includes the fluorescent substance.
108. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected the metallic wiring  
on the substrate;  
a sealing resin for sealing the semiconductor light-emitting element is included; and  
the sealing resin includes the fluorescent substance.
109. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected the metallic wiring  
on the substrate;  
a sealing resin for sealing the semiconductor light-emitting element is included; and  
the sealing resin includes the fluorescent substance.
110. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected the metallic wiring  
on the substrate;  
a sealing resin for sealing the semiconductor light-emitting element is included; and  
the sealing resin includes the fluorescent substance.

111. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected the metallic wiring  
on the substrate;

a sealing resin for sealing the semiconductor light-emitting element is included; and  
the sealing resin includes the fluorescent substance.

112. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion; and  
the fluorescent substance is filled in the recessed portion.

113. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion; and  
the fluorescent substance is filled in the recessed portion.

114. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion; and  
the fluorescent substance is filled in the recessed portion.

115. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion; and

the fluorescent substance is filled in the recessed portion.

116. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion; and  
the fluorescent substance is filled in the recessed portion.

117. (Newly added) The semiconductor light-emitting device according to Claim 112, wherein  
the recessed portion is formed by a frame disposed on the substrate.

118. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion;  
a sealing resin is filled in the recessed portion; and  
the fluorescent substance is disposed on the sealing resin.

119. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion;  
a sealing resin is filled in the recessed portion; and  
the fluorescent substance is disposed on the sealing resin.

120. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion;

a sealing resin is filled in the recessed portion; and  
the fluorescent substance is disposed on the sealing resin.

121. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion;  
a sealing resin is filled in the recessed portion; and  
the fluorescent substance is disposed on the sealing resin.

122. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate and disposed in a recessed portion;  
a sealing resin is filled in the recessed portion; and  
the fluorescent substance is disposed on the sealing resin.

123. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic  
wiring on the substrate;  
a reflector for reflecting at least a part of outgoing light from the semiconductor  
light-emitting element is included;  
a sealing resin for sealing the semiconductor light-emitting element and transmitting  
reflected light from the reflector is included; and  
the fluorescent substance is included in the sealing resin.

124. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein  
the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is included in the sealing resin.

125. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is included in the sealing resin.

126. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

the fluorescent substance is included in the sealing resin.

127. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein

the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;  
a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;  
a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and  
the fluorescent substance is included in the sealing resin.

128. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;  
a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;  
a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;  
a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and  
a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

129. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein  
the base substance is a substrate provided with metallic wiring;  
the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;  
a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

130. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

131. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

132. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a shielding body for shielding light directly emitted from the semiconductor light-emitting element to the outside of the semiconductor light-emitting device is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

133. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and



a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

134. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

135. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

136. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein

- the base substance is a substrate provided with metallic wiring;
- the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;
- at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;
- a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;
- a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and
- a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

137. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein

- the base substance is a substrate provided with metallic wiring;
- the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;
- at least a light-emitting section of the semiconductor light-emitting element is disposed in a recessed portion in the substrate;
- a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;
- a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and
- a layer of the fluorescent substance is formed on a surface of the reflector that reflects light.

138. (Newly added) The semiconductor light-emitting device according to Claim 80, wherein

- the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

139. (Newly added) The semiconductor light-emitting device according to Claim 82, wherein the base substance is a substrate provided with metallic wiring; the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

140. (Newly added) The semiconductor light-emitting device according to Claim 84, wherein the base substance is a substrate provided with metallic wiring; the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

141. (Newly added) The semiconductor light-emitting device according to Claim 86, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

142. (Newly added) The semiconductor light-emitting device according to Claim 88, wherein

the base substance is a substrate provided with metallic wiring;

the semiconductor light-emitting element is electrically connected to the metallic wiring on the substrate;

a reflector for reflecting at least a part of outgoing light from the semiconductor light-emitting element is included;

a sealing resin for sealing the semiconductor light-emitting element and transmitting reflected light from the reflector is included; and

a layer of the fluorescent substance is formed on a surface of the sealing resin that reflects light.

143. (Newly added) A semiconductor light-emitting device, comprising:

a base substance;

a semiconductor light-emitting element on the base substance, wherein the semiconductor light-emitting element has outgoing light having emission wavelengths of 390 to 420 nm, exclusive of 390 nm so that the outgoing light is almost invisible to human eyes;

a first fluorescent substance;

a second fluorescent substance; and

a third fluorescent substance, wherein

the first fluorescent substance has red outgoing light having emission wavelengths with its main emission peak in a wavelength range of 600 to 670 nm;

the second fluorescent substance has green outgoing light having emission wavelengths with its main emission peak in a wavelength range of 500 to 540 nm;

the third fluorescent substance has blue outgoing light having emission wavelengths with its main emission peak in a wavelength range of 410 to 480 nm; and

the sum of colors of light emitted from the first, second and third fluorescent substances is a white color.

144. (Newly added) The semiconductor light-emitting device according to claim 143, wherein the first fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$M_2O_2S$ : Eu (M is any one or more elements selected from La, Gd and Y);

$0.5MgF_2 \cdot 3.5MgO \cdot GeO_2$ : Mn;

$Y_2O_3$ : Eu,

$Y(P, V)O_4$ : Eu; and

$YVO_4$ : Eu;

the second fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$RMg_2Al_{16}O_{27}$ : Eu, Mn (R is any one or both elements selected from Sr and Ba);

$RMgAl_{10}O_{17}$ : Eu, Mn (R is any one or both elements selected from Sr and Ba);

ZnS: Cu;

$SrAl_2O_4$ : Eu;

$\text{SrAl}_2\text{O}_4$  : Eu, Dy;

$\text{ZnO}$ : Zn;

$\text{Zn}_2\text{Ge}_2\text{O}_4$  : Mn;

$\text{Zn}_2\text{SiO}_4$  : Mn; and

$\text{Q}_3\text{MgSi}_2\text{O}_8$  : Eu, Mn (Q is any one or more elements selected from Sr, Ba and Ca);

and

the third fluorescent substance is composed of any one or more selected from a fluorescent substance group consisting of:

$\text{A}_{10}(\text{PO}_4)_6\text{Cl}_2$  : Eu (A is any one or more elements selected from Sr, Ca, Ba, Mg and Ce);

$\text{XMg}_2\text{Al}_6\text{O}_{27}$  : E (X is any one or both elements selected from Sr and Ba);

$\text{XMgAl}_{10}\text{O}_{17}$  : Eu (X is any one or both elements selected from Sr and Ba);

$\text{ZnS}$ : Ag;

$\text{Sr}_{10}(\text{PO}_4)_6\text{Cl}_2$  : Eu;

$\text{Ca}_{10}(\text{PO}_4)_6\text{F}_2$  : Sb;

$\text{Z}_3\text{MgSi}_2\text{O}_8$  : Eu (Z is any one or more elements selected from Sr, Ca and Ba);

$\text{SrMgSi}_2\text{O}_8$  : Eu;

$\text{Sr}_2\text{P}_2\text{O}_7$  : Eu; and

$\text{CaAl}_2\text{O}_4$  : Eu, Nd.

145. (Newly added) The semiconductor light-emitting device according to Claim 143, wherein, assuming the total amount as 100 weight %,

the first fluorescent substance is between 50 weight % and 70 weight % inclusive;

the second fluorescent substance is between 7 weight % and 20 weight % inclusive;

and

the third fluorescent substance is between 20 weight % and 30 weight % inclusive.

146. (Newly added) The semiconductor light-emitting device according to Claim 145, wherein the sealing resin includes the first, second and third fluorescent substances; and

the proportion of the total weight of the first, second and third fluorescent substances to the weight of the sealing resin is between 0.5 and 1 inclusive.

147. (Newly added) A light-emitting display device comprising;  
a light source using the semiconductor light-emitting device according to Claim 64;  
a light guiding plate for guiding light from the light source; and  
red, green and blue color filters for transmitting light from the light guiding plate and dividing the light; the light-emitting display device, wherein  
outgoing light from the semiconductor light-emitting device has a wavelength distribution that matches spectral characteristics of the color filters.

148. (Newly added) The light-emitting display device according to Claim 147, wherein at least one of the following is adjusted so that the wavelength distribution of the outgoing light from the semiconductor light-emitting device matches spectral characteristics of the color filters:

the emission wavelength of the semiconductor light-emitting element;  
the emission wavelength of the first fluorescent substance;  
the emission wavelength of the second fluorescent substance;  
the emission wavelength of the third fluorescent substance;  
the mixture proportions of the first, second and third fluorescent substances; and  
the proportion of the total weight of the first, second and third fluorescent substances to the weight of the sealing resin.

149. (Newly added) The light-emitting display device according to Claim 147, wherein the light-emitting display device is a liquid crystal display device.

150. (Newly added) The light-emitting display device according to Claim 148, wherein the light-emitting display device is a liquid crystal display device.

151. (Newly added) The light-emitting display device according to Claim 80, wherein

the emission wavelength of the outgoing light is 400 to 420 nm.

152. (Newly added) The light-emitting display device according to Claim 82, wherein the emission wavelength of the outgoing light is 400 to 420 nm.

153. (Newly added) The light-emitting display device according to Claim 84, wherein the emission wavelength of the outgoing light is 400 to 420 nm.

154. (Newly added) The light-emitting display device according to Claim 86, wherein the emission wavelength of the outgoing light is 400 to 420 nm.

155. (Newly added) The light-emitting display device according to Claim 88, wherein the emission wavelength of the outgoing light is 400 to 420 nm.

156. (Newly added) The light-emitting display device according to Claim 143, wherein the emission wavelength of the outgoing light is 400 to 420 nm.